
Programmatic Challenges of Pb-Free Technology for the High-Reliability Electronics Industry

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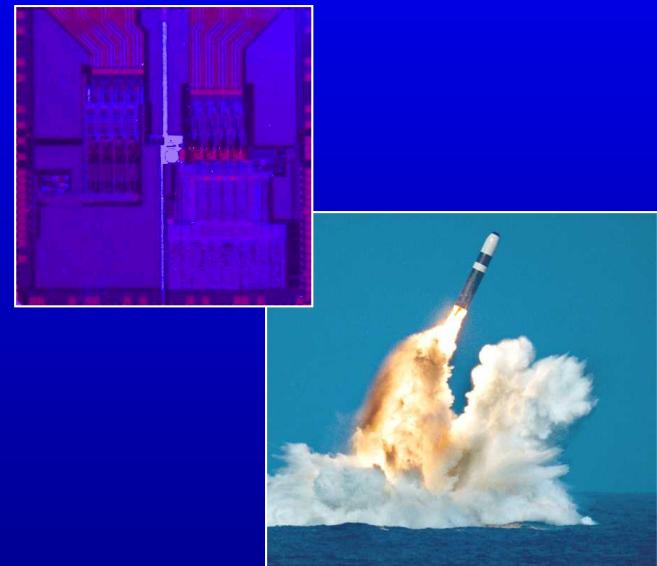


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High-Reliability Electronics

- ◆ 63Sn-37Pb (Sn-Pb) interconnection technology has a proven track-record of providing manufacturability, reliability, and sustainability across the aerospace and defense (A&D) industries
- ◆ There is no apparent technical basis to change to a Pb-free solution in order to realize, or to even improve upon, these successes.



Why fix, what isn't broken ???

Changing Business Climate

- ◆ Non-technical forces are driving the way in which the A&D industry delivers electronics assemblies.

In-house manufacturing capacity is being replaced with outside supplier services

“Re-enterprising” has driven decisions to curtail some manufacturing capabilities, including electronics assembly.

Outside suppliers are being forced into Pb-free solutions by their commercial customers

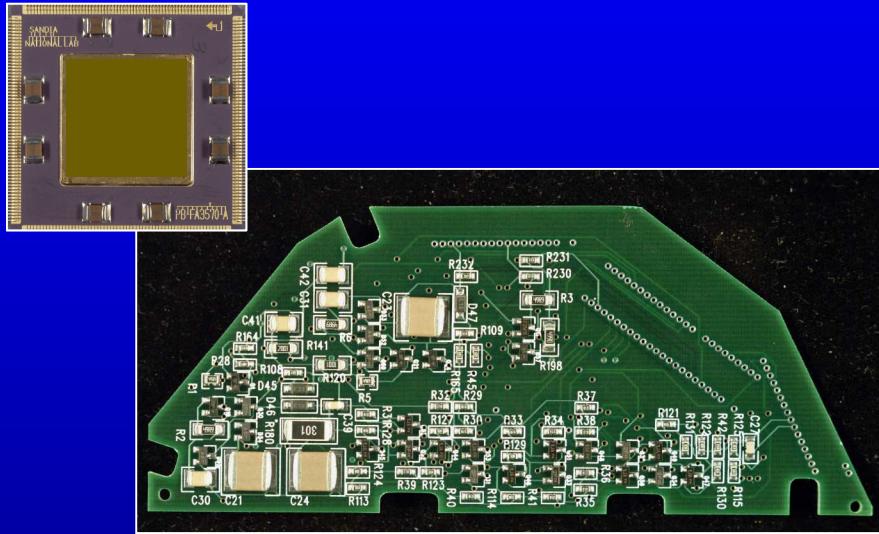
It is not in the supplier’s best interest, from either a manufacturing engineering or a business perspective, to maintain both a SnPb and a Pb-free assembly capability.

The A&D industry must addresses a future in which a Pb-free solution is the only option for its commercially-supplied electronics.



Changing Business Climate

◆ Performance-based procurement ...



- ◆ A&D institutions have had to relinquish control over materials, components, and manufacturing to commercial suppliers – *some are even overseas*.

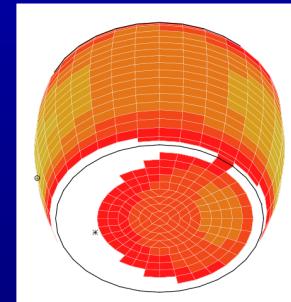
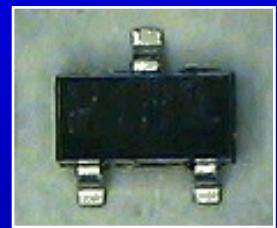
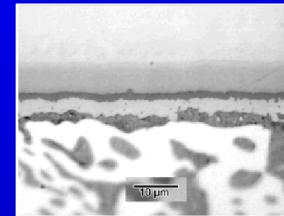
The Loss of Sn-Pb Technology

- ◆ The viability of Sn-Pb solders will not be lost due to a “step-function” decline in materials availability.
- ◆ Instead, the viability of Sn-Pb technology will be lost because of cost premiums and protracted schedules.
- ◆ However, an important concern is not that there will be a phase-out of Sn-Pb technology ...
... rather, it is when and, in particular, when with respect to the specific program schedules.
- ◆ Case in point ... *The need to change solder alloys that then requires revalidation and requalification.*

The Path Forward

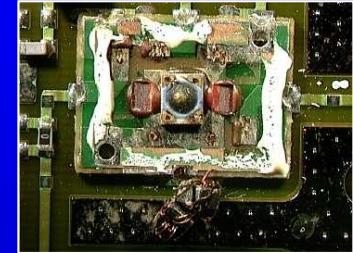
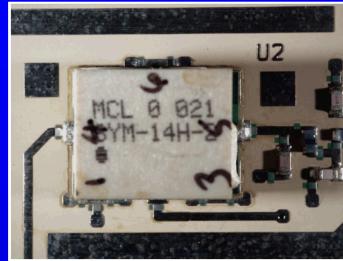
- ◆ The electronics industry as a *whole* has a better foothold on Pb-free technology after 20 years, than it has had on Sn-Pb technology after 90 years of use.

- Fundamental materials science
- Surface finishes
- Fluxes / pastes/ cored wire
- Manufacturing (... *not quite*)
- Reliability (*test and modeling*)
- Supply chain management

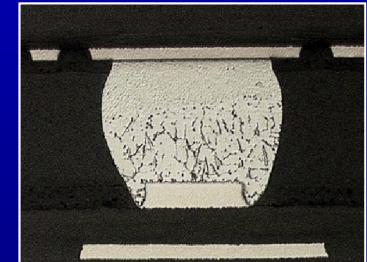


The Most Pressing Technical Issues

- ◆ Surface finishes:
 - Sn whiskers
 - Alternative finishes
- ◆ Materials:
 - Multiple solder alloy
- ◆ Manufacturing:
 - Heat, heat, heat, ...
- ◆ Long-term reliability
 - Mixed solders
 - Shock and vibration



Sn whiskers in COTS hybrids



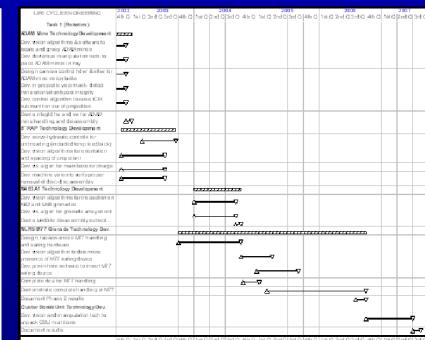
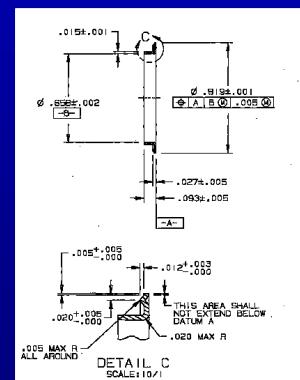
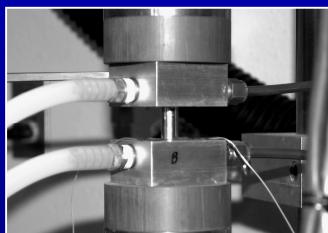
*SAC305/Sn-Pb mixed solder joints:
legacy and new hardware*

The Path Forward

- ◆ A successful Pb-free solution must be executed as a:

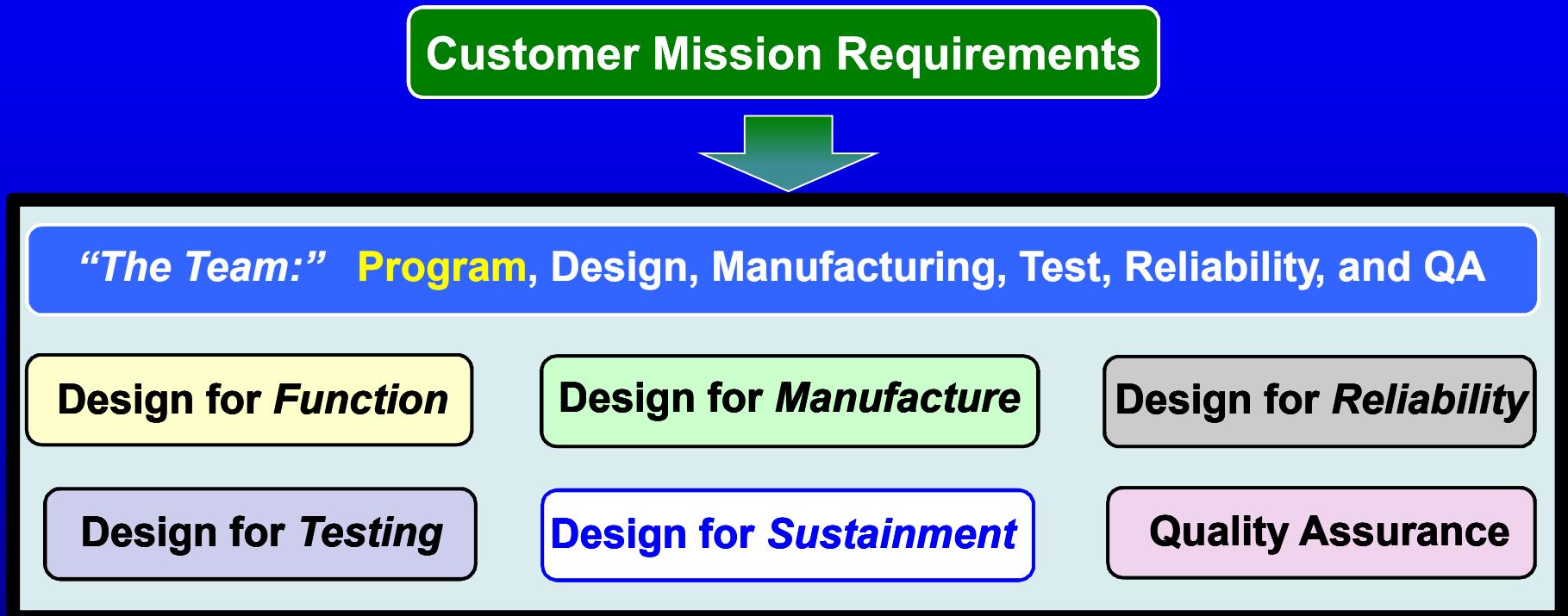
*Technology – program
partnership*

- ◆ It has been the experience at Sandia, through the development of a Pb-free product that is concurrent with COTS implementation, that technology and programmatic functions **must support each other**.



The “10,000 ft. Level”

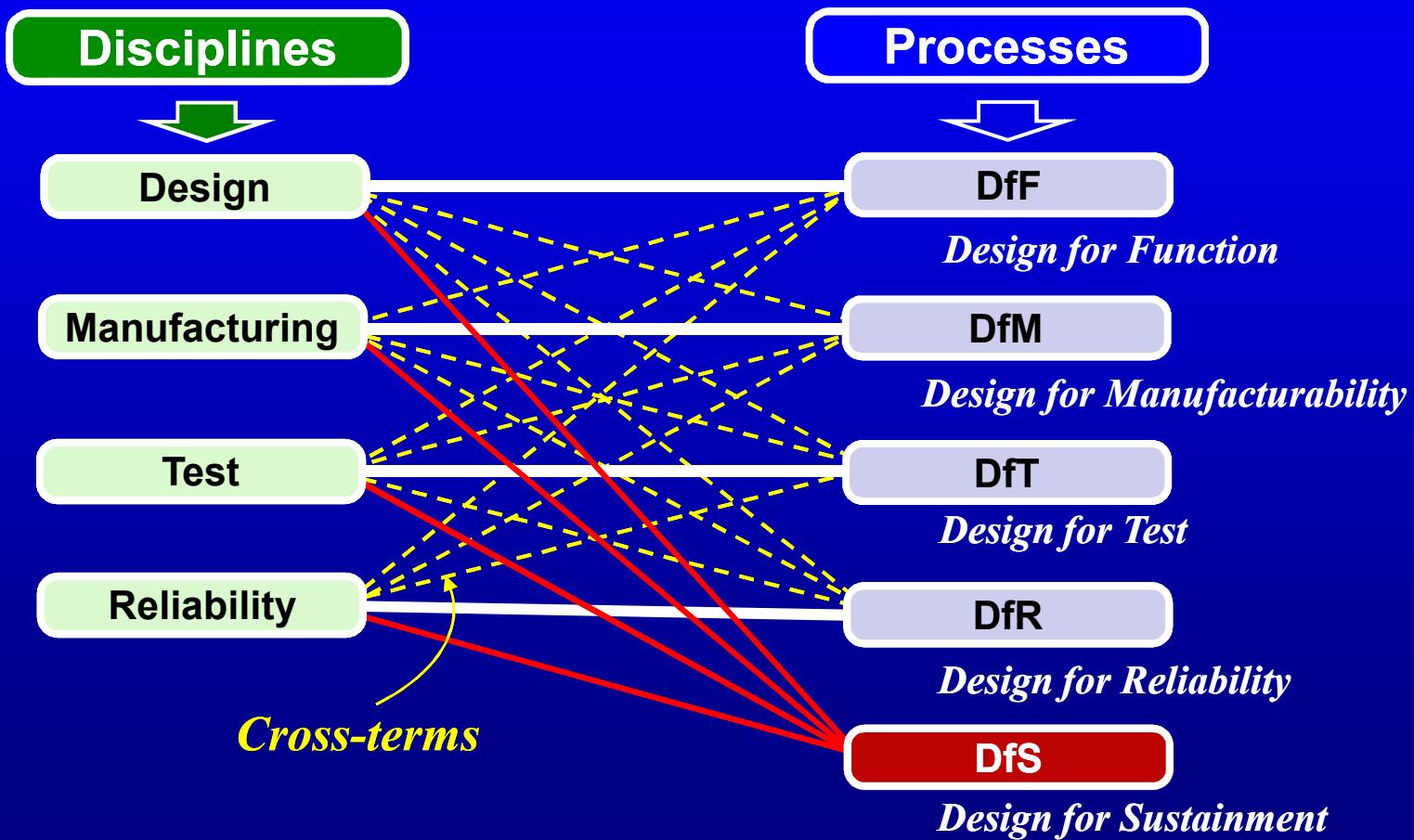
- ◆ A fully integrated approach is the *only* path that works.



A&D companies are learning the value of this approach ...
... *sometimes, “the hard way”*.

Why We *MUST* Do Business in this Manner

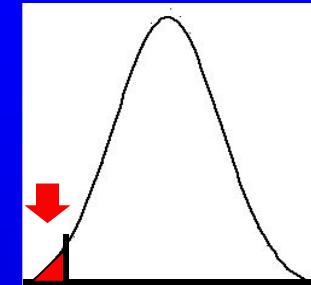
- Often, the development of high-reliability, complex systems fails to appreciate the “**cross-term**” effects.



Example: The COTS “1% Defect” Problem

- ◆ Low-frequency (1%) component-level failures have been observed with commercial off-the-shelf (COTS) and MIL-COTS parts, using Sn-Pb solder:

- ◆ Multi-layer chip capacitor
- ◆ Glass-body diodes
- ◆ Tantalum capacitors
- ◆ Chip resistors



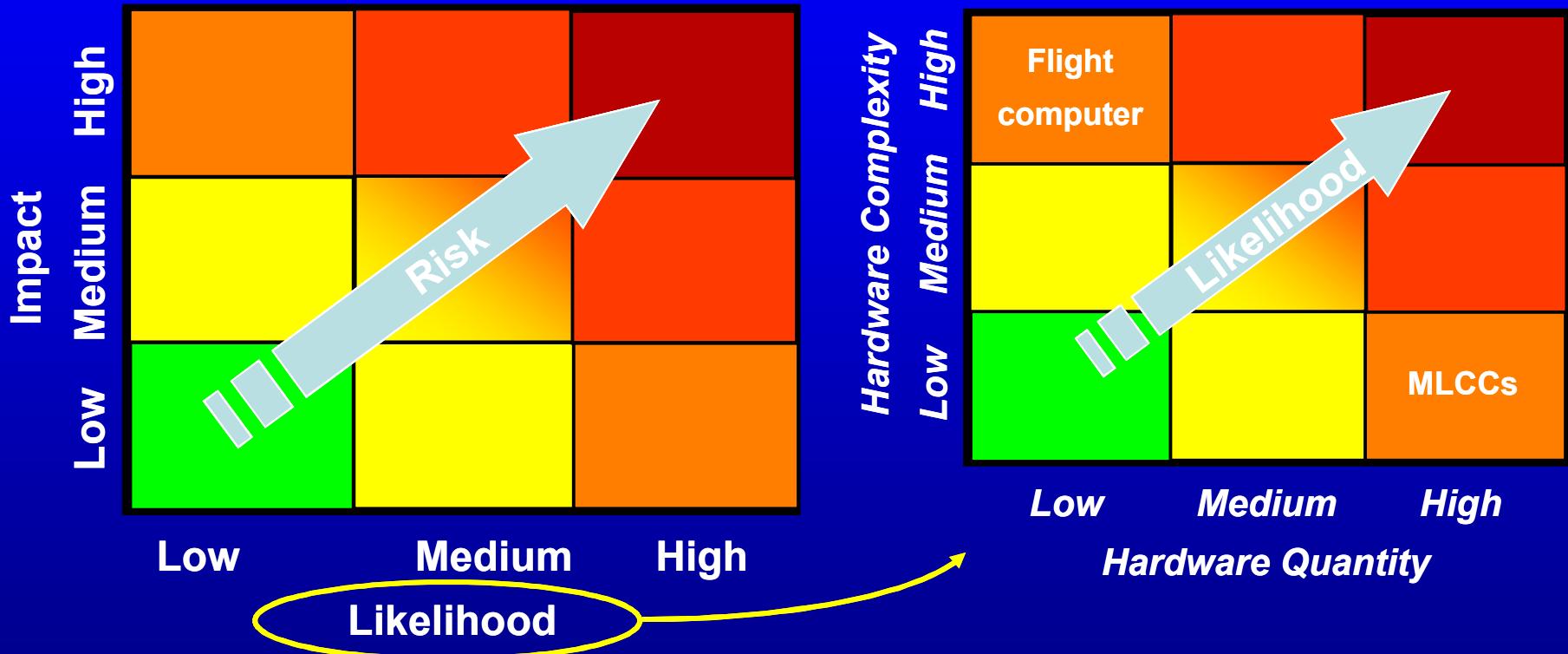
“1%” Problem

Commercial products cannot be blamed entirely for the “1%” defect issue; we may have already been headed down this road even with MIL-grade components, due to greater system complexity and increased functionality requirements.

- ◆ The A&D industry *cannot* expect assistance from the supplier base, even with price premiums. These low failure rates are not critical to their prime customers, the commercial electronics industry.

Approach: Understand the Risk

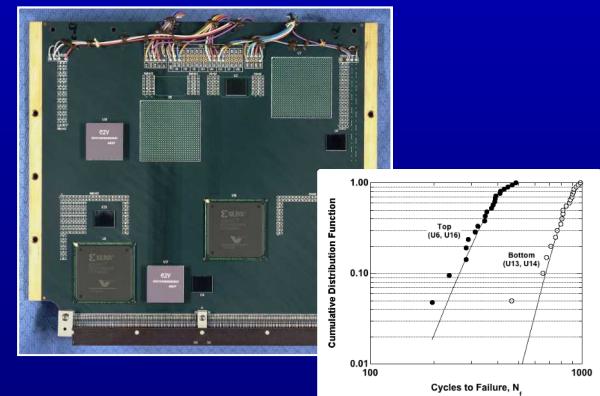
- Often, the A&D Industry neglects the fact that the “Likelihood” regime has two contributing factors.



The failure of low-complexity components (or “mature technologies”), if present in large quantities within a sub-system, can significantly impact the long-term reliability of the overall system.

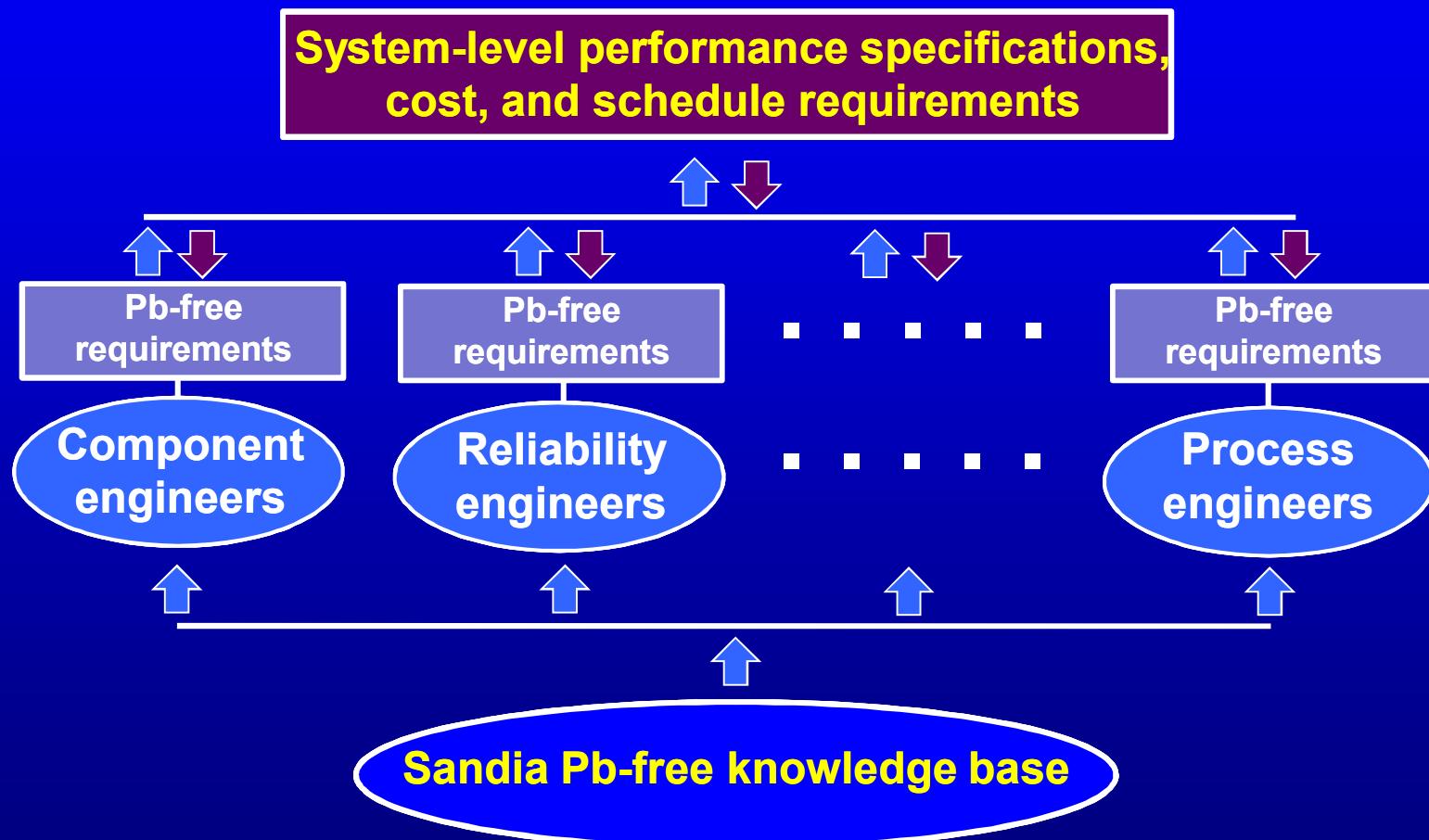
Approach: Environmental Stress Screening

- ◆ Materials, process and reliability SMEs are sensitized to complex as well as “out-of-the-spotlight” technologies.
 - Assess components, mechanical structures, etc.
 - No component or sub-system is beyond scrutiny!
 - Value of failure modes effects analysis (FMEA).
- ◆ Best approach to finding defects: develop screening test methodologies performed at the supplier (to keep part warranties) or in-house (loss of warranties).
 - Characterization test vehicles
 - Accelerated aging environments (HALT, HAST, etc.)
 - Apply small-sample statistical analysis techniques

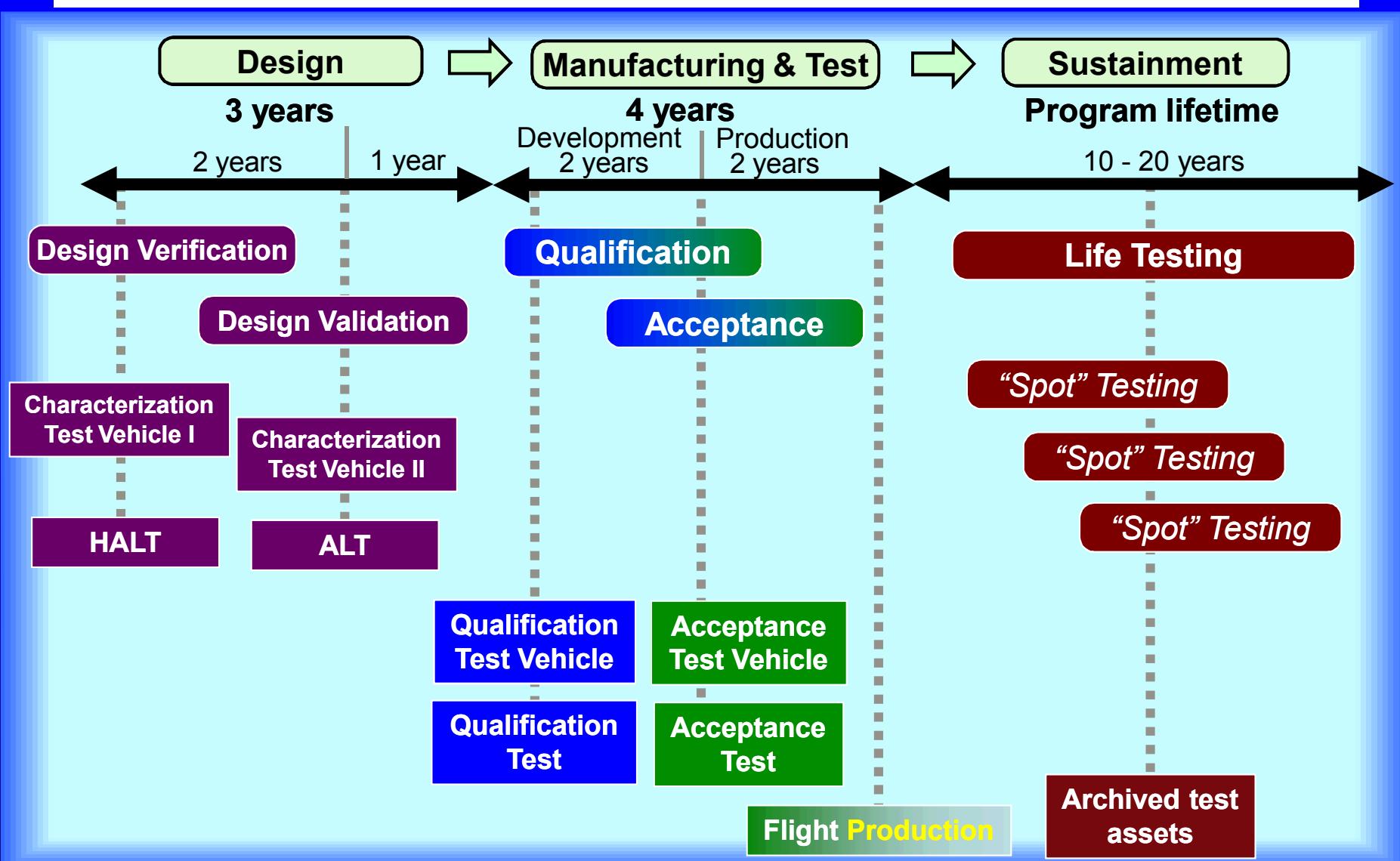


Tailor the Information Flow to the Organization

- ◆ Sandia is a “bottom-up” organization with respect to Pb-free technology ... *that is our starting point.*

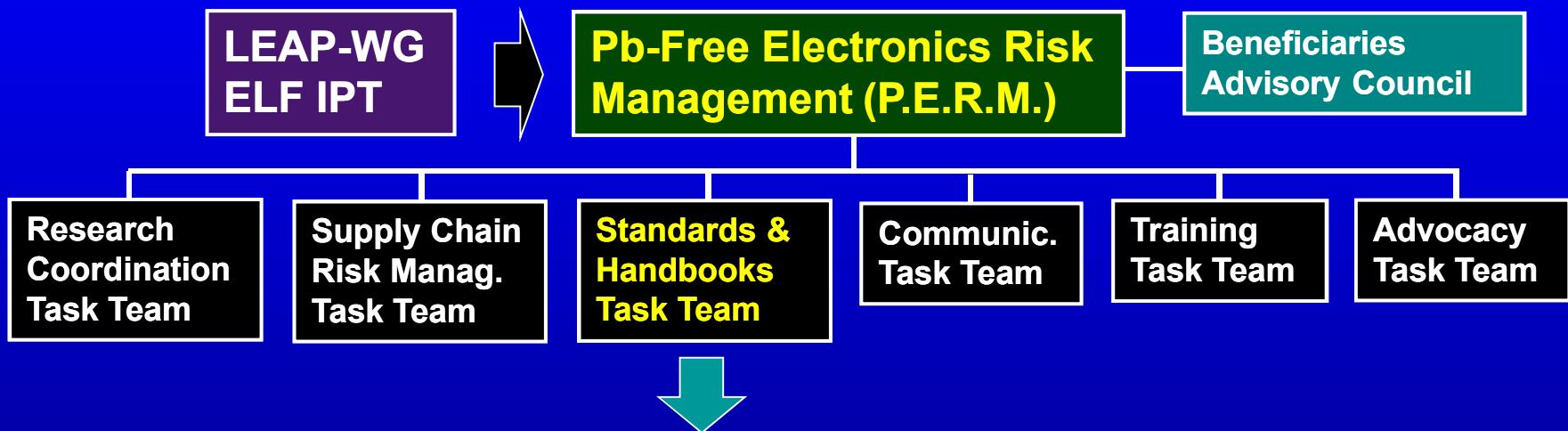


Awareness of Schedule and Investment



Standards, Specifications, and Guidelines

- ◆ Organizations such as the IPC, ASTM, JEDEC and ISO are developing ANSI consensus documents that address specifically Pb-free soldering technology.



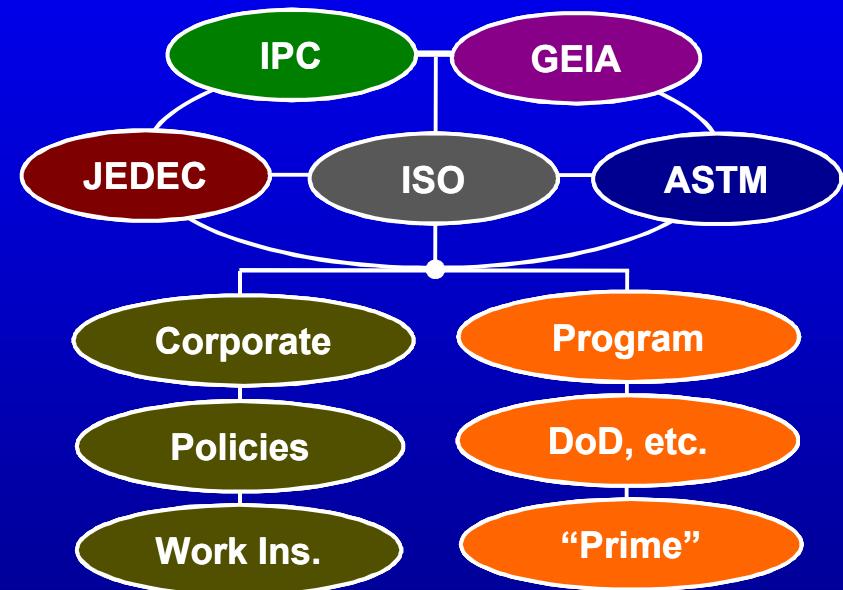
GEIA-STD-0005-3, “*Performance Testing for Aerospace and High Performance [AHP] Electronic Interconnects Containing Pb-free Solder and Finishes*”

- Tests methods: thermal cycling, shock and vibration, etc.
- Test vehicles
- Data analysis

... Where the *Real* Work Begins ...

- ◆ The challenge is to integrate all of these resources into one or more documents that can be executed by the program or across a company technology:

- Supply chain management
- Design for Function
- Design for Manufacturing
- Design for Test
- Design for Reliability and Quality Assurance (QA)
- Design for Sustainment



- ◆ The condensed timeline of Pb-free implementation will require an *integrated effort* by technical personnel *and* program management to develop these documents.

Summary

- ◆ Today, programmatic details have surpassed the technical knowledge towards developing a Pb-free solution in the Aerospace and Defense (A&D) industry.
- ◆ Performance-based procurement and commercial off-the-shelf (COTS) supply chains have added their own “complexities” to the challenges.
- ◆ For as “standardized” as we would wish the A&D industry to be, different organization cultures as well as product lines necessitate the tailoring of standards and practices for their successful integration.

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Summary

- ◆ Planning can only go so far ... The system must be exercised in order to address the programmatic challenges that are a part of a Pb-free solution.
- ◆ Washington D.C. funding sources are becoming increasingly *unsympathetic* to excessive cost overruns and schedule delays*.
- ◆ This prevailing attitude can affect the continued support of existing programs, and the ability of an organization to win future contracts*.

* Observation first made by author in April 2010, Huntsville, AL.

